CFP2 Terminal Pins: Straight Actuator Color: Gray

Ultra-Miniature Pushbutton Switches







RoHS Compliant

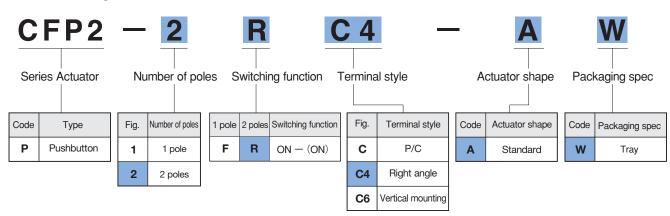
Features -

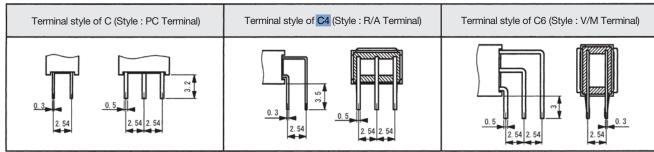
- 1. Ultra-miniature pushbutton switch for high density mounting.
- Washable.
- 3. Terminal pin pitch: 2.54 mm.
- 4. Independent detent mechanism ensures light operational feel.
- 5. Clip contact mechanism for long-term contact reliability.
- 6. Gold-plated contacts.

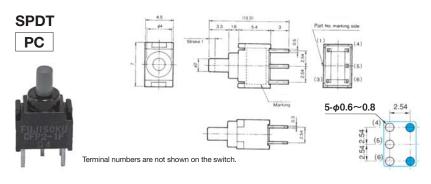
Specifications

Rating	Max.	0.4VA (28VDC max	(.)	
	Min.	1μA 20mVDC		
Initial contact resistance		100m Ω max.	(1.5mA 200µVAC)	
Dielectric strength		250VAC 1 minute		
Insulation resistance		500MΩ min. (250VDC)		
Electrical life		10,000 operations at max.rating, 30,000 operations at min.rating,		
Mechanical life		30,000 cycles		
Operating force		1.47±0.98N		
Operating temperature range		-40~+85°C		
Storage temperature range		−40~+85°C		



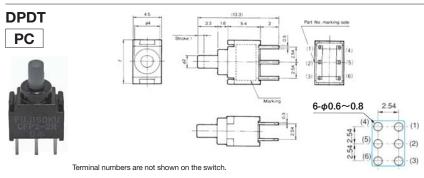






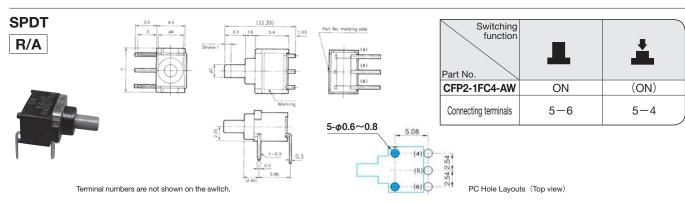
Switching function Part No.	1	±
CFP2-1FC-AW	ON	(ON)
Connecting terminals	5-6	5-4

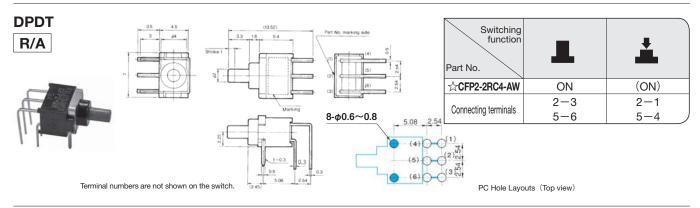
PC Hole Layouts (Top view)



Switching function Part No.	1	<u></u>
☆CFP2-2RC-AW	ON	(ON)
0	2-3	2-1
Connecting terminals	5-6	5-4

PC Hole Layouts (Top view)





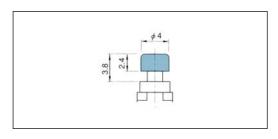
 $\ensuremath{\mathrm{\%}}$ The above PC Hole Layouts are top view drawings.

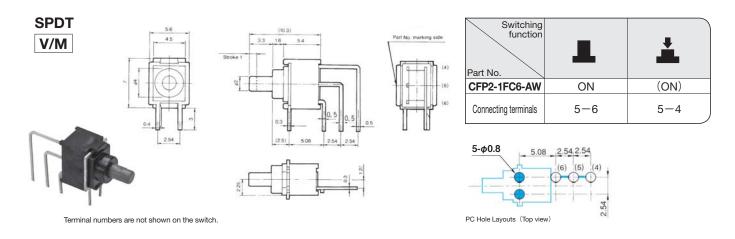
■ Optional Accessories

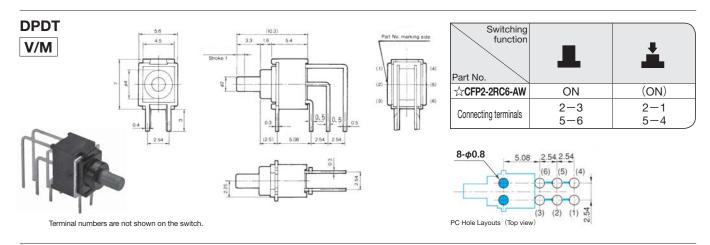
			(Sold separately)
Part Name	Dimension	Color	Part Number
	Gloss finish	White	140000481453
Color Cap	 94	_	140000481452
Color Cap			140000481451
	ABS resin	Gray	140000481450

■Color Cap Mounting

(ON): Momentary.







^{*} The above pcb hole dimengion, it is a top view drawiing when we fix the switch.

■Handling Specifications (CFP2)

1. Soldering Specifications

(1)Manual Soldering

Device : Soldering iron

350°C, Max.; 3 seconds, Max.

(2)Auto Soldering

Device: Jet wave type or dip type

260°C, Max.; 3-5 seconds, Max. (One time)

Total dip time: Within 10 seconds

 Pre-heating should be done at temperatures from 80°C to 120°C and within 120 seconds

(3)When soldering two or more terminals to a common land, use solder resist to separate them

2. Flux Cleaning

- (1)Solvents: Fluorine or Alcohol type
- (2)Cleaning after soldering should be done after the PC board is exposed to room temperature (30°C or below) for 1 to 2 hours.
- (3)Do not use ultrasonic cleaning.

■ Packaging Specifications

